

Vishay Siliconix

P-Channel 12 V (D-S) MOSFET



Marking code: 03

PRODUCT SUMMARY					
V _{DS} (V)	-12				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -4.5 V	0.035				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -2.5 V	0.045				
$R_{DS(on)}$ max. (Ω) at V_{GS} = -1.8 V	0.059				
Q _g typ. (nC)	9				
I _D (A) ^a	-5.1				
Configuration	Single				

FEATURES

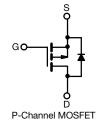
- TrenchFET® power MOSFET
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- · Load switch
- PA switch



ORDERING INFORMATION				
Package	SOT-23 (TO-236)			
Lead (Pb)-free	Si2333CDS-T1-E3			
Lead (Pb)-free and halogen-free	Si2333CDS-T1-GE3			

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	-12	
Gate-source voltage		V_{GS}	± 8	V
	T _C = 25 °C		-7.1	
Continuous drain surrent /T 150 °C)	T _C = 70 °C	1 , [-5.7	
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	-5.1 ^{b, c}	
	T _A = 70 °C	1	-4.0 b, c	A
Pulsed drain current		I _{DM}	-20	
Continuous source-drain diode current	T _C = 25 °C		-1.0	
	T _A = 25 °C	I _S	-0.63 b, c	
Maximum power dissipation	T _C = 25 °C		2.5	
	T _C = 70 °C	1 5 [1.6	14/
	T _A = 25 °C	P _D	1.25 ^{b, c}	W
	T _A = 70 °C	1	0.8 b, c	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT		
Maximum junction-to-ambient b, d	t ≤ 5 s	R _{thJA}	75	100	°C/W	
Maximum junction-to-case (drain)	Steady state	R _{thJC}	40	50	C/VV	

Notes

- a. $T_C = 25$ °C
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 5 s
- d. Maximum under steady state conditions is 166 °C/W

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static	STWIDOL	1231 CONDITIONS	IVIII4.	1115.	IVIAA.	ONT	
Drain-source breakdown voltage	V	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu A$	-12			V	
	V _{DS}	VGS = 0 V, ID = -230 μπ	-12	-13	_	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	$I_D = -250 \mu A$			-	mV/°C	
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J	V V I 050 ·· A	- 0.4	2.6	-	V	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-0.4	-	-1	<u> </u>	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	-	-	± 100	nA	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	-1	μA	
	200	$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	-	-	-10	ļ	
On-state drain current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-20	-	-	Α	
		$V_{GS} = -4.5 \text{ V}, I_D = -5.1 \text{ A}$	-	0.0285	0.035	Ω	
Drain-source on-state resistance a	R _{DS(on)}	$V_{GS} = -2.5 \text{ V}, I_D = -4.5 \text{ A}$	-	0.036	0.045		
		$V_{GS} = -1.8 \text{ V}, I_D = -2.0 \text{ A}$	-	0.046	0.059		
Forward transconductance ^a	9 _{fs}	$V_{DS} = -5 \text{ V}, I_D = -5.3 \text{ A}$	-	18.5	-	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	1225	-	pF	
Output capacitance	C _{oss}	$V_{DS} = -6 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	315	-		
Reverse transfer capacitance	C _{rss}		-	260	-		
Total colorabases	0	$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -5.1 \text{ A}$	-	15	25		
Total gate charge	Q_g		-	9	15	1	
Gate-source charge	Q_{gs}	$V_{DS} = -6 \text{ V}, V_{GS} = -2.5 \text{ V}, I_D = -5.1 \text{ A}$	-	1.9	-	nC	
Gate-drain charge	Q _{qd}		-	3.8	-		
Gate resistance	R_{g}	f = 1 MHz	-	4	-	Ω	
Turn-on delay time	t _{d(on)}		-	13	20		
Rise time	t _r	$V_{DD} = -6 \text{ V}, R_1 = 6 \Omega, I_D = -1 \text{ A},$	-	35	60	ns	
Turn-off delay time	t _{d(off)}	V_{GEN} = -4.5 V, R_g = 1 Ω	-	45	70		
Fall time	t _f		-	12	20		
Drain-Source Body Diode Characterist	ics						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	-1		
Pulse diode forward current ^a	I _{SM}		-	-	-20	A	
Body diode voltage	V _{SD}	I _S = -1.0 A	-	-0.7	-1.2	V	
Body diode reverse recovery time	t _{rr}	<u> </u>	-	32	50	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = -1.0 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	20	40	nC	
Reverse recovery fall time	ta	$T_{\text{J}} = 25 ^{\circ}\text{C}$	-	16	-		
Reverse recovery rise time	t _b		-	16	-	ns	

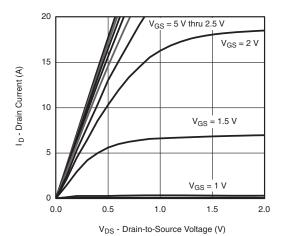
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

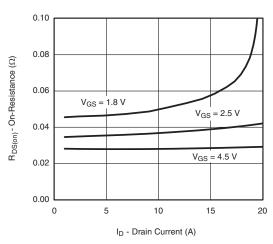
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



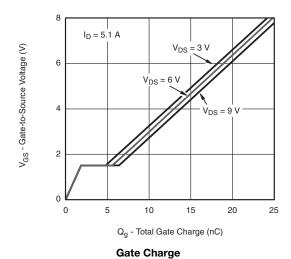
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

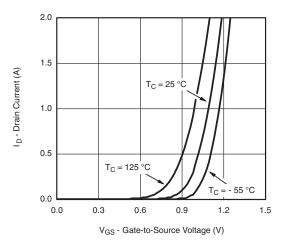


Output Characteristics

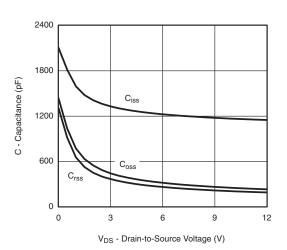


On-Resistance vs. Drain Current and Gate Voltage

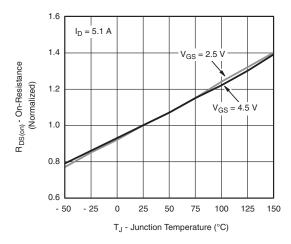




Transfer Characteristics



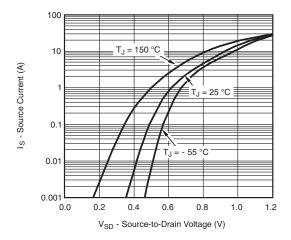
Capacitance



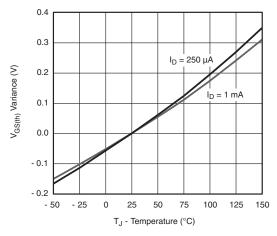
On-Resistance vs. Junction Temperature



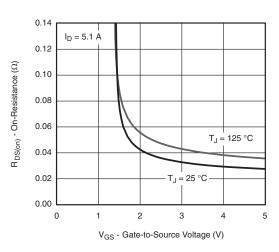
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



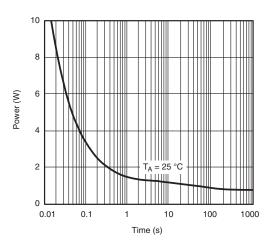
Source-Drain Diode Forward Voltage



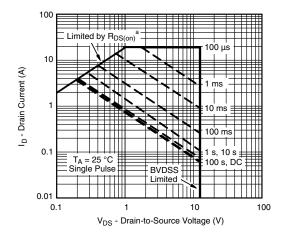
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power



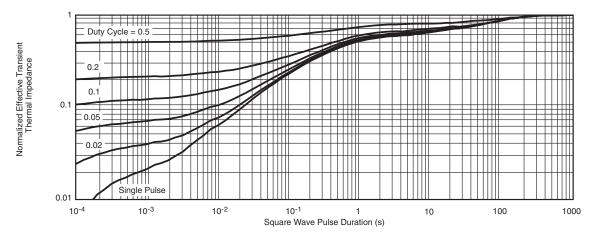
Safe Operating Area

Note

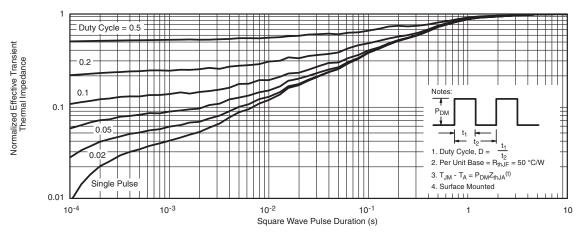
a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



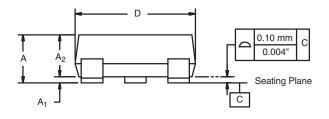
Normalized Thermal Transient Impedance, Junction-to-Foot

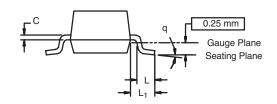
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?68717.

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SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95	BSC	0.037	4 Ref	
e ₁	1.90 BSC		0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K. 09-	Jul-01				

DWG: 5479

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RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE

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